

1 Characteristics

Table 1. Absolute ratings (limiting values at $T_j = 25^\circ\text{C}$, unless otherwise specified)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			200	V
I _{FRM}	Repetitive peak forward current	DO-15 ⁽¹⁾	t _p = 5 μs, F = 5 kHz	60	A
		SMA, SMB			
I _{F(RMS)}	RMS forward current	DO-15		60	A
		SMA, SMB			
I _{F(AV)}	Average forward current, δ = 0.5	DO-15	T _{lead} = 90° C	2	A
		SMA, SMB	T _C = 90° C		
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms Sinusoidal		75	A
T _{stg}	Storage temperature range			-65 to + 175	° C
T _j	Maximum operating junction temperature			175	° C

1. On infinite heatsink with 10 mm lead length

Table 2. Thermal parameters

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to lead	Lead Length = 10 mm on infinite heatsink	DO-15	45	$^\circ\text{C/W}$
	Junction to case		SMA, SMB	30	

Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			3	μA
		$T_j = 125^\circ\text{C}$			2	20	
$V_F^{(2)}$	Forward voltage drop	$T_j = 25^\circ\text{C}$	$I_F = 6\ \text{A}$			1.20	V
		$T_j = 25^\circ\text{C}$	$I_F = 2\ \text{A}$		0.89	1.0	
		$T_j = 100^\circ\text{C}$			0.76	0.85	
		$T_j = 150^\circ\text{C}$			0.70	0.80	

1. Pulse test: $t_p = 5\ \text{ms}$, $\delta < 2\%$

2. Pulse test: $t_p = 380\ \mu\text{s}$, $\delta < 2\%$

To evaluate the conduction losses use the following equation:

$$P = 0.68 \times I_{F(AV)} + 0.06 I_{F(RMS)}^2$$

Table 4. Dynamic characteristics

Symbol	Parameter	Test conditions	Min.	Typ	Max.	Unit
t_{rr}	Reverse recovery time	$I_F = 1\text{ A}$, $dI_F/dt = -50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25^\circ\text{C}$		23	30	ns
		$I_F = 1\text{ A}$, $dI_F/dt = -100\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $T_j = 25^\circ\text{C}$		15	20	
I_{RM}	Reverse recovery current	$I_F = 2\text{ A}$, $dI_F/dt = -200\text{ A}/\mu\text{s}$, $V_R = 160\text{ V}$, $T_j = 125^\circ\text{C}$		3	4	A
t_{fr}	Forward recovery time	$I_F = 2\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$, $V_{FR} = 1.1 \times V_{Fmax}$, $T_j = 25^\circ\text{C}$		40		ns
V_{FP}	Forward recovery voltage	$I_F = 2\text{ A}$, $dI_F/dt = 100\text{ A}/\mu\text{s}$, $T_j = 25^\circ\text{C}$		2.0		V

Figure 1. Peak current versus duty cycle

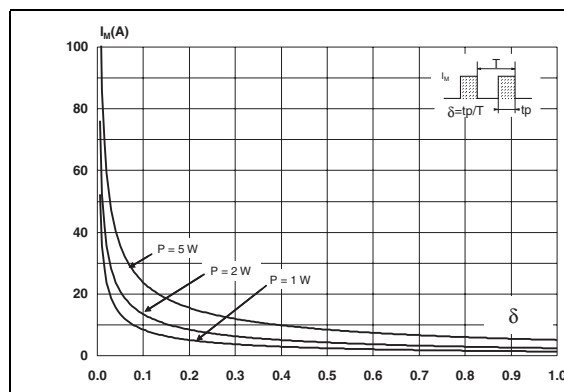


Figure 2. Forward voltage drop versus forward current (typical values)

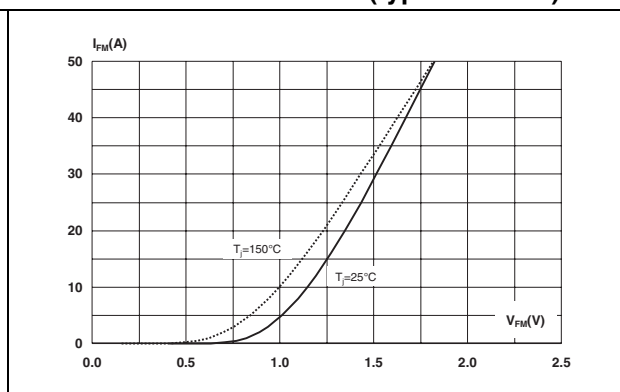


Figure 3. Forward voltage drop versus forward current (maximum values)

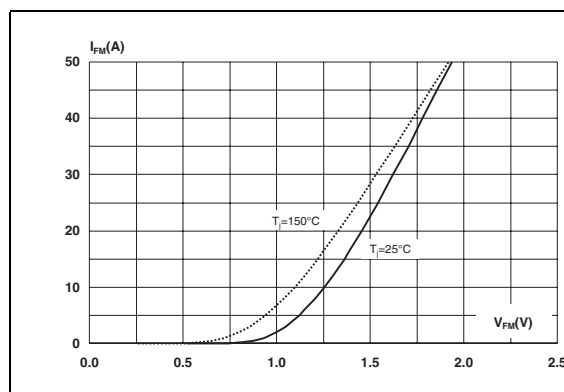


Figure 4. Relative variation of thermal impedance junction to case versus pulse duration (SMA)

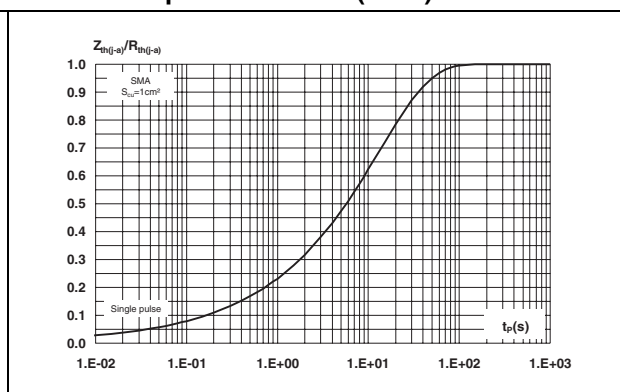


Figure 5. Relative variation of thermal impedance junction to case versus pulse duration (SMB)

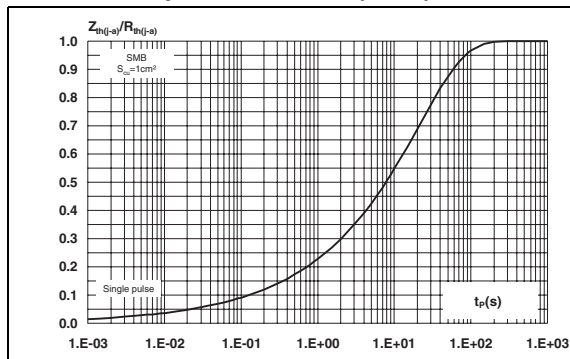


Figure 6. Relative variation of thermal impedance junction to case versus pulse duration (DO-15)

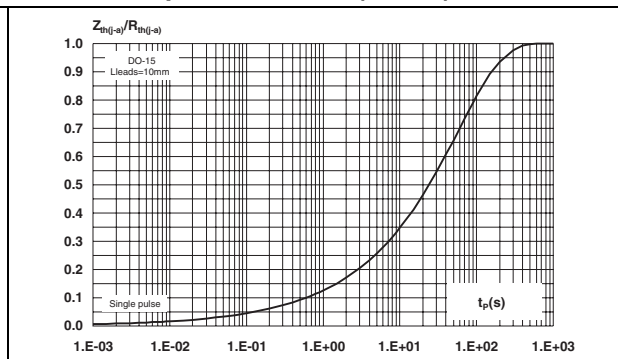


Figure 7. Junction capacitance versus reverse applied voltage (typical values)

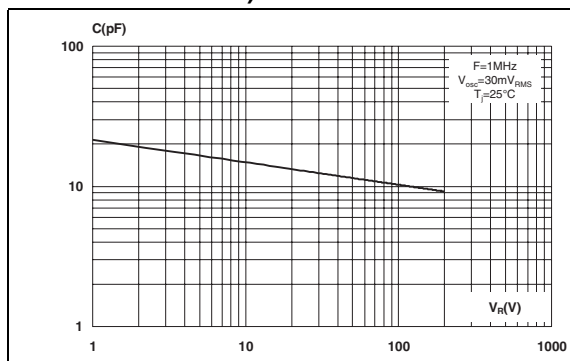


Figure 8. Reverse recovery charges versus di_F/dt (typical values)

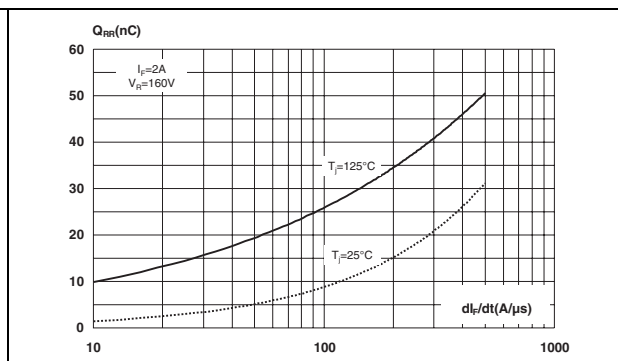


Figure 9. Reverse recovery time versus di_F/dt (typical values)

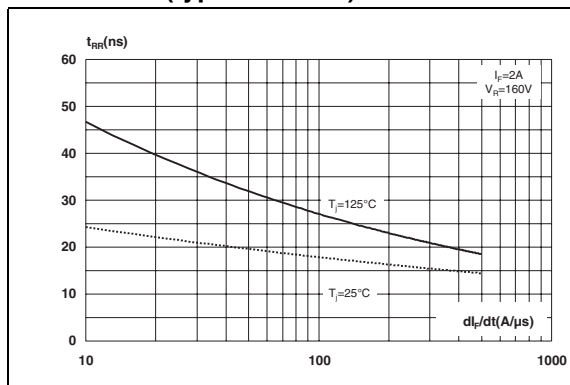


Figure 10. Peak reverse recovery current versus di_F/dt (typical values)

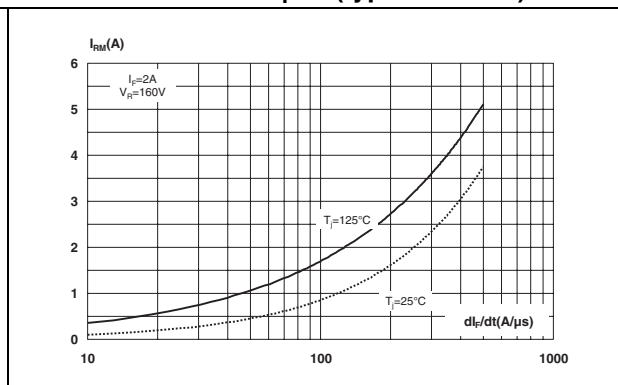


Figure 11. Dynamic parameters versus junction temperature

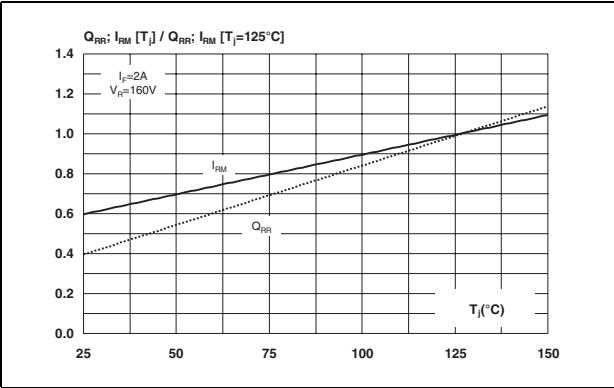


Figure 12. Thermal resistance, junction to ambient, versus copper surface under each lead - SMA/SMB (epoxy FR4, e_{cu} = 35 μm)

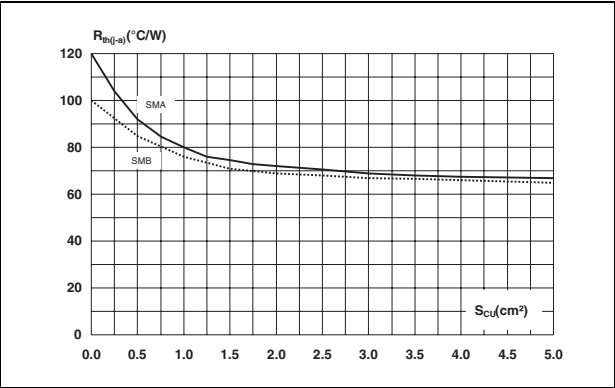
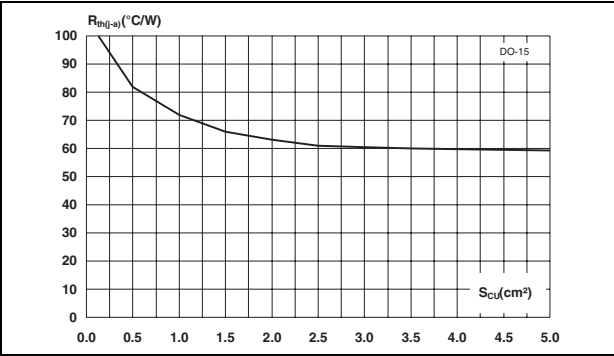
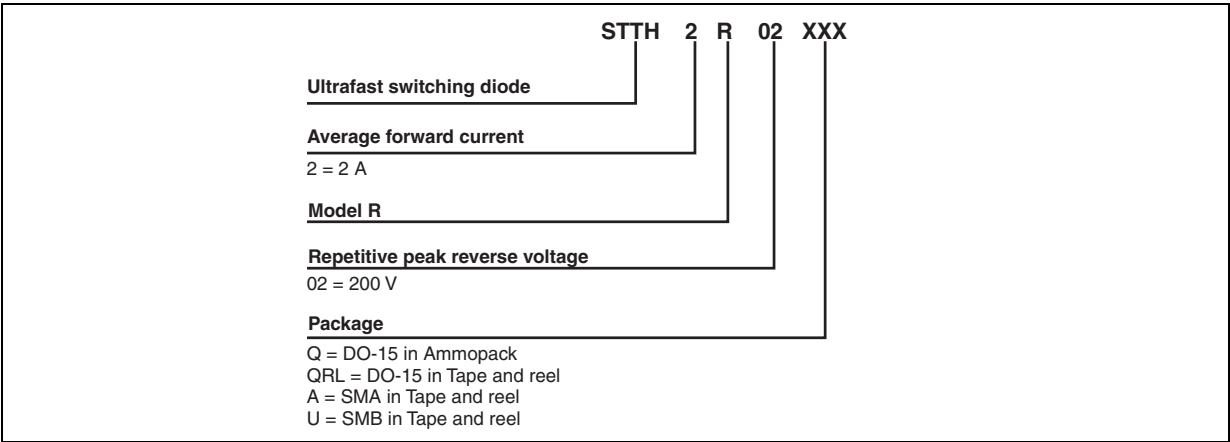


Figure 13. Thermal resistance, junction to ambient, versus copper surface under each lead DO-15 (epoxy FR4, e_{cu} = 35 μm)



2 Ordering information scheme



3 Package information

Epoxy meets UL94, V0

Table 5. DO-15 Dimensions

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	6.05	6.75	0.238	0.266
B	2.95	3.53	0.116	0.139
C	26	31	1.024	1.220
D	0.71	0.88	0.028	0.035

Table 6. SMA dimensions

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A1	1.90	2.03	0.075	0.080
A2	0.05	0.20	0.002	0.008
b	1.25	1.65	0.049	0.065
c	0.15	0.41	0.006	0.016
E	4.80	5.60	0.189	0.220
E1	3.95	4.60	0.156	0.181
D	2.25	2.95	0.089	0.116
L	0.75	1.60	0.030	0.063

Figure 14. SMA footprint (dimensions in mm)

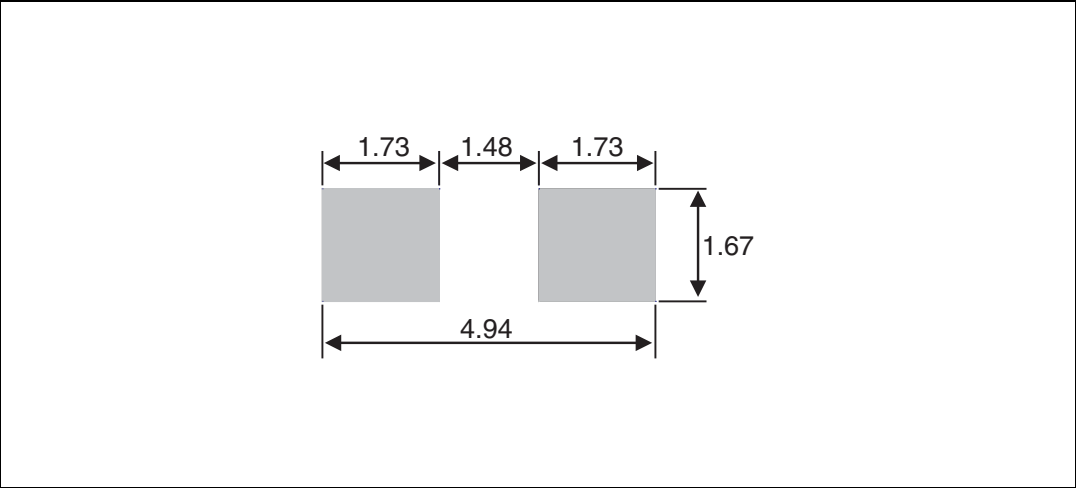
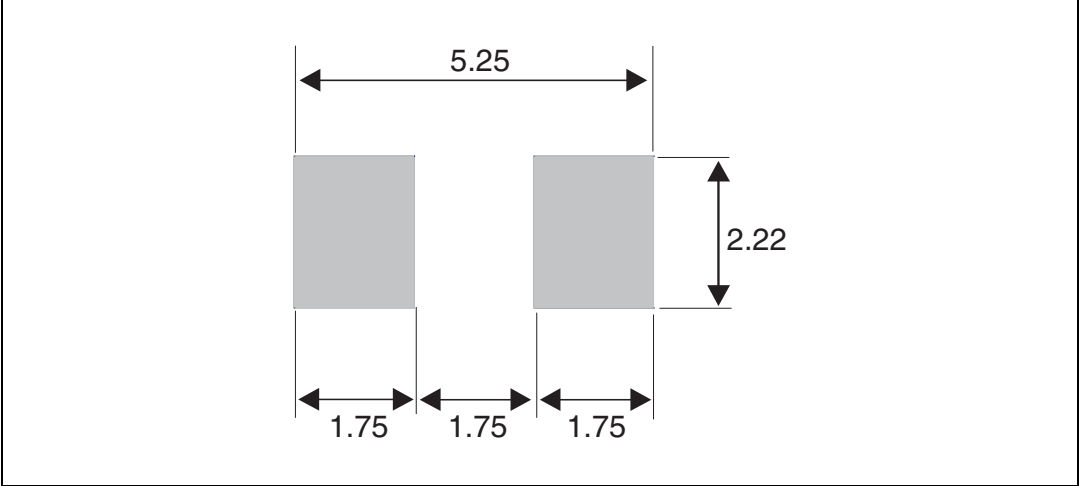


Table 7. SMB dimensions

REF.	DIMENSIONS					
	Millimeters			Inches		
	Min.		Max.	Min.		Max.
A1	1.90	2.15	2.45	0.075	0.085	0.096
A2	0.05	0.15	0.20	0.002	0.006	0.008
b	1.95		2.20	0.077		0.087
c	0.15		0.41	0.006		0.016
E	5.10	5.40	5.60	0.201	0.213	0.220
E1	4.05	4.30	4.60	0.159	0.169	0.181
D	3.30	3.60	3.95	0.130	0.142	0.156
L	0.75	1.15	1.60	0.030	0.045	0.063

Figure 15. SMB footprint (dimensions in mm)



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

4 Ordering information

Part Number	Marking	Package	Weight	Base qty	Delivery mode
STTH2R02Q	STTH2R02	DO-15	0.4 g	1000	Ammopack
STTH2R02QRL	STTH2R02	DO-15	0.4 g	6000	Tape and reel
STTH2R02A	R2A	SMA	0.068 g	5000	Tape and reel
STTH2R02U	R2U	SMB	0.12 g	2500	Tape and reel

5 Revision history

Date	Revision	Description of Changes
03-May-2006	1	First issue
13-Oct-2006	2	Maximum T_j set to 175° C for all packages in Table 1.

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